

DOCKET No.: 122302.00001

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Oliver Chyan, et al.

Serial No.: 10/600,039

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Art Unit: 2818

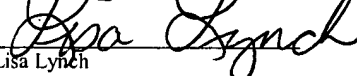
Examiner: Mai Huong C. Tran

For: **METHOD OF USING MATERIALS BASED ON RUTHENIUM AND
IRIDIUM AND THEIR OXIDES, AS A CU DIFFUSION BARRIER, AND
INTEGRATED CIRCUITS INCORPORATING THE SAME**

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P.O. Box 1450
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CERTIFICATE OF MAILING UNDER 37 C.F.R. 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 3, 2004.


Lisa Lynch

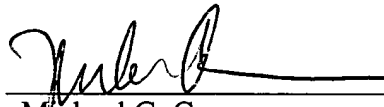
RESPONSE TO RESTRICTION REQUIREMENT

In response to the Office Action mailed November 12, 2004, Applicant hereby elects, without traverse, to prosecute in this application Set of Claims 1-10, Set of Claims 25-29, Set of Claims 31-32 and Set of Claims 33-34, comprising Species I, drawn to a method of controlling copper diffusion using a layer of RuO₂ as a diffusion stuffer having a layer of Ru on the inter-level dielectric substrate.

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Respectfully submitted,



Michael G. Cameron

Reg. No. 50,298

Jackson Walker L.L.P.

2435 North Central Expressway, Suite 600

Richardson, Texas 75080

Tel: (972) 744-2934

Fax: (972) 238-3334 or (972) 744-2909

December 3, 2004

Date